Device Material Content

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Package: 484 caBGA
Total Device Weight 1612.354 mg

Package Code: BBG484
Products: LFCPNX-100

Assembly: ASEK
Size (mm): 19 x 19
Lead pitch (mm): 0.8
MSL: 3
Reflow max (ºC): 260

	% of Material to Total Pkg. Wt.	Material Weight (mg)	% of Substance Wt.	Material Substance Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.700%	27.411	1.700%	27.411	Silicon chip	7440-21-3	100.000%	8.216 x 7.19 mm
Mold Compound	65.882%	1062.257	56.190%	905.976	Silica(Fused)(1)	60676-86-0	85.288%	Mold Compound: KE-G1250AAS
			3.161%	50.961	Silica(Fused)(2)	7631-86-9	4.797%	
			3.161%	50.961	Epoxy resin	Trade Secret	4.797%	
			3.161%	50.961	Phenol resin	Trade Secret	4.797%	
			0.211%	3.397	Carbon Black	1333-86-4	0.320%	
D/A Epoxy	0.620%	9.997	0.534%	8.606	Silver (Ag)	7440-22-4	86.091%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.037%	0.592	2,2-dimethyl-1,3 Propanediyl Bismethacrylate	1985-51-9	5.919%	
			0.030%	0.492	A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol	-	4.919%	
			0.01%	0.09997	Perfluoropolyoxyalkane ether	925918-64-5	1.000%	
			0.012%	0.188	2-[[2,2 bis[[(1-oxoally)oxy]methyl]butoxy]methyl]-2-ethyl-1.3-propanediyl diacrylate	94108-97-1	1.883%	
			0.001%	0.019	bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3	0.188%	
Wire	0.290%	4.676	0.285%	4.595	Copper	7440-50-8	98.275%	CuPdAu+ (Au-PCC Plus)
			0.005%	0.073	Palladium	7440-05-3	1.555%	
			0.000%	0.008	Gold	7440-57-5	0.170%	
Solder Balls	11.510%	185.579	11.107%	179.084	Tin (Sn)	7440-31-5	96.500%	SAC305
			0.345%	5.567	Silver (Ag)	7440-22-4	3.000%	
			0.058%	0.928	Copper (Cu)	7440-50-8	0.500%	
Substrate	6.050%	97.551	0.763%	12.298	Continuous Filament Fiber Glass	65997-17-3	12.607%	BT Resin CCL-HL832NX-A
			0.300%	4.845	Inorganic filler	21645-51-2	4.967%	
			0.416%	6.708	Bismaleimide Triazine	105391-33-1	6.877%	
			0.416%	6.708	Epoxy Resin	25722-66-1	6.877%	
			0.415%	6.692	Other Resin	9003-36-5	6.860%	
			3.740%	60.300	Copper	7440-50-8	61.813%	
Foil	2.647%	42.681	2.408%	38.824	Copper	7440-50-8	90.963%	Cu Foil
			0.200%	3.230	Nickel	7440-02-0	7.567%	
			0.039%	0.627	Gold	7440-57-5	1.470%	
Solder Mask	11.300%	182.203	0.452%	7.287	Morpholine derivative	Trade secret	4.000%	Solder mask PSR4000 AUS 308
			5.198%	83.811	Barium Sulfate	7727-43-7	45.999%	
			0.113%	1.824	Silica	7631-86-9	1.001%	
			0.452%	7.287	Talc	14807-96-6	4.000%	
			2.712%	43.729	Dipropylene Glycol Monomethyl Ether	34590-94-8	24.000%	
			2.373%	38.263	Epoxy Resin	85954-11-6	21.000%	
	100.000%	1612.354	100.000%	1612.354			800.000%	

Note:

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